Jue Li

List of Publications by Year
in descending order

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19	334	933447 10	1058476 14
papers	citations	h-index	g-index

19	19	19	246
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	MEMS reliability. , 2020, , 851-876.		6
2	Vertical cracking of Cu-Sn solid-liquid interdiffusion bond under thermal shock test. Materials Today: Proceedings, 2017, 4, 7093-7100.	1.8	6
3	MEMS Reliability. , 2015, , 744-763.		3
4	Study on thermomechanical reliability of power modules and thermal grease pump-out mechanism. , 2015, , .		3
5	Microstructural Characterization and Mechanical Performance of Wafer-Level SLID Bonded Au-Sn and Cu-Sn Seal Rings for MEMS Encapsulation. Journal of Electronic Materials, 2015, 44, 4533-4548.	2.2	36
6	Shock Impact Reliability and Failure Analysis of a Three-Axis MEMS Gyroscope. Journal of Microelectromechanical Systems, 2014, 23, 347-355.	2.5	41
7	Reliability assessment of a MEMS microphone under mixed flowing gas environment and shock impact loading. Microelectronics Reliability, 2014, 54, 1228-1234.	1.7	13
8	Localized recrystallization and cracking of lead-free solder interconnections under thermal cycling â€“ ERRATUM. Journal of Materials Research, 2012, 27, 978-978.	2.6	1
9	Reliability assessment of MEMS devices — A case study of a 3 axis gyroscope. , 2012, , .		9
10	Finite element modeling for reliability assessment of solder interconnections in a power transistor. , 2012, , .		0
11	The reliability of component boards studied with different shock impact repetition frequencies. Microelectronics Reliability, 2012, 52, 1445-1453.	1.7	3
12	Dependence of recrystallization on grain morphology of Sn-based solder interconnects under thermomechanical stress. Journal of Alloys and Compounds, 2012, 540, 32-35.	5.5	12
13	Hyperelastic Property Measurements of Heat-Cured Silicone Adhesives by Cyclic Uniaxial Tensile Test. Journal of Electronic Materials, 2012, 41, 2613-2620.	2.2	2
14	On the effects of temperature on the drop reliability of electronic component boards. Microelectronics Reliability, 2012, 52, 165-179.	1.7	30
15	Inhomogeneous deformation and microstructure evolution of Snâ€“Ag-based solder interconnects during thermal cycling and shear testing. Microelectronics Reliability, 2012, 52, 1112-1120.	1.7	61
16	Finite element analyses and lifetime predictions for SnAgCu solder interconnections in thermal shock tests. Soldering and Surface Mount Technology, 2011, 23, 161-167.	1.5	14
17	Localized recrystallization and cracking of lead-free solder interconnections under thermal cycling. Journal of Materials Research, 2011, 26, 2103-2116.	2.6	39
18	A novel impact test system for more efficient reliability testing. Microelectronics Reliability, 2010, 50, 1125-1133.	1.7	14

#	Article	IF	Citations
19	Reliability of Lead-Free Solder Interconnections in Thermal and Power Cycling Tests. IEEE Transactions on Components and Packaging Technologies, 2009, 32, 302-308.	1.3	41